

CLAIMS:

- Sub A1
1. An electrically conductive silicone rubber composition having improved adhesion, comprising
- 5 (A) 100 parts by weight of an organopolysiloxane having at least two aliphatic unsaturated groups in a molecule,
- (B) 0.1 to 100 parts by weight of finely divided silica,
- (C) 30 to 700 parts by weight of a metal powder or an electrically conductive metal-plated powder,
- 10 (D) 0.1 to 20 parts by weight of an adhesive aid, and
- (E) a curing agent in an amount sufficient to cure the organopolysiloxane.
2. The silicone rubber composition of claim 1, wherein
- 15 the metal powder of component (C) is a silver powder.
3. The silicone rubber composition of claim 1, wherein component (C) is a metal-plated silica powder having a construction comprising silica covered with a nickel layer
- 20 which in turn is covered with a gold layer.
4. The silicone rubber composition of claim 1, wherein component (D) is a compound having at least one alkoxy group or epoxy group or both in a molecule.
- 25 5. The silicone rubber composition of claim 1, wherein component (D) is an organosilicon compound having in a molecule at least two different groups selected from the class consisting of SiH, epoxy, alkoxy and alkenyloxy groups.
- 30 6. The silicone rubber composition of claim 1, wherein component (D) is an organosilicon compound having in a molecule at least one SiH group and at least one group containing an aromatic ring and/or a carbonyl group.
- 35 7. The silicone rubber composition of claim 1, wherein the curing agent (E) is an organic peroxide.

